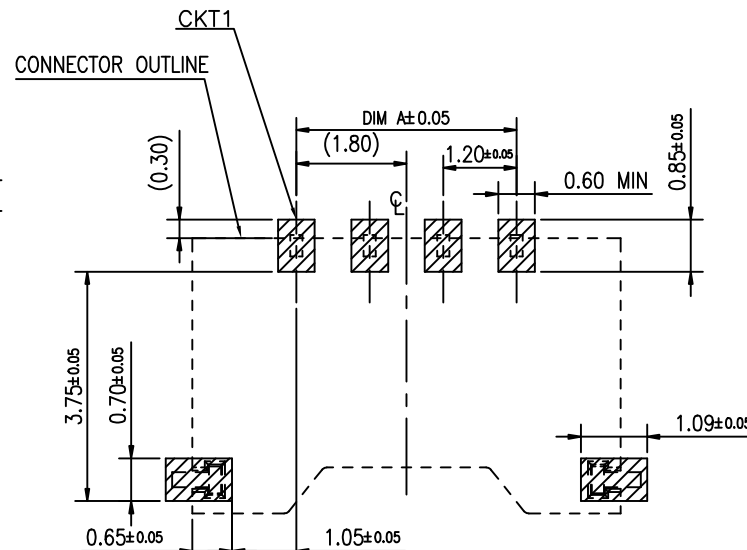
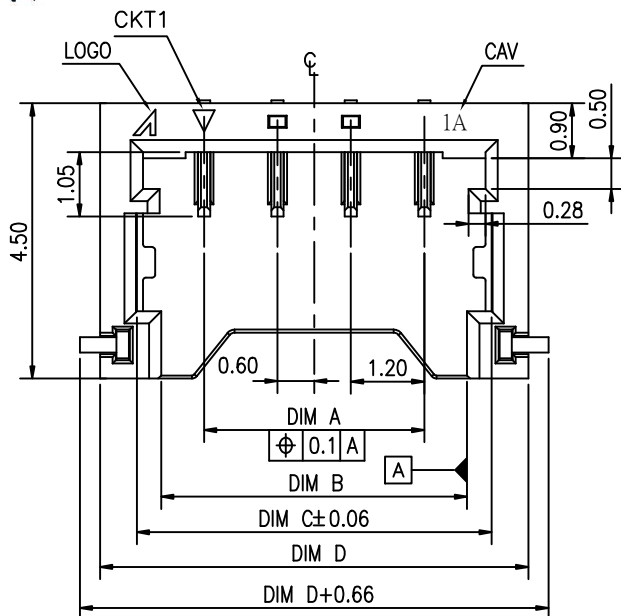
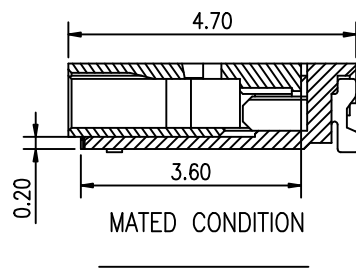
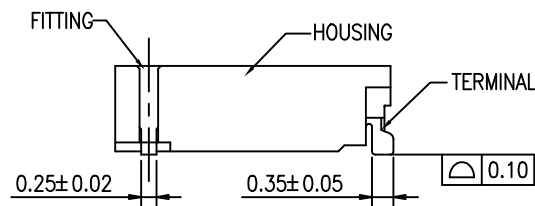
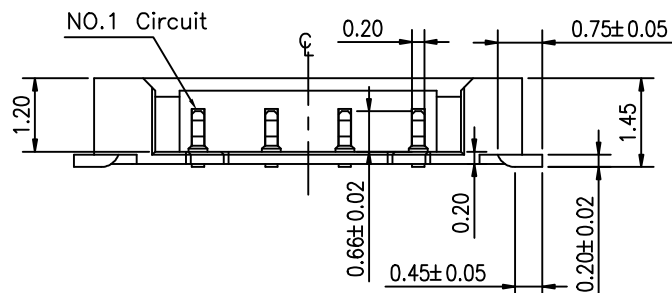




RECOMMENDED PCB LAYOUT
PCB THICKNESS 1.20±0.05
(TOP VIEW)



NOTES:

1. MATERIAL:

1.1 HOUSING: HALOGEN FREE PLASTIC, HIGH TEMP;
UL94V-0.

1.2 CONTACT: COPPER ALLOY.

1.3 FITTING NAIL: COPPER ALLOY

2. FINISH:

2.1 TERMINAL CONTACT: 50u" MIN. NICKEL UNDERPLATING OVERALL.

1: GOLD FLASH ON CONTACT AND SOLDER AREA

N: 50u" MIN MATT TIN ON CONTACT AND SOLDER AREA

C: 15u" GOLD PLATING ON CONTACT AND GOLD FLASH ON SOLDER AREA

T: 10u" GOLD PLATING ON CONTACT AND GOLD FLASH ON SOLDER AREA

B: 5u" GOLD PLATING ON CONTACT AND GOLD FLASH ON SOLDER AREA

Q: 5u" GOLD PLATING ON CONTACT AND 1u" GOLD ON SOLDER AREA

3: 1u" GOLD PLATING ON CONTACT AND 1u" GOLD ON SOLDER AREA

2.2 FITTING NAIL: 50u" MIN. NICKEL UNDERPLATING OVERALL.

100u" MIN. MATT TIN PLATING

3. SPEC. PLS. REFER TO PS-50269-xxxxx-xxx

4. PACKAGE PLS. REFER TO 51220-xxxxx-05-TRP

5. PART NUMBER

51273-XXX X X-XXX

NO OF CKT

PACKING

0: TAPE & REEL

PLATING

1: GOLD FLASH

N: MATT TIN

C: 15u" GOLD PLATING ON CONTACT

T: 10u" GOLD PLATING ON CONTACT

B: 5u" GOLD PLATING ON CONTACT

Q: 5u" GOLD PLATING ON CONTACT

3: 1u" GOLD PLATING ON CONTACT

CKT	Dim A	Dim B	Dim C	Dim D
2	1.2	2.6	3.3	4.6
3	2.4	3.8	4.5	5.8
4	3.6	5.0	5.7	7.0
5	4.8	6.2	6.9	8.2
6	6.0	7.4	8.1	9.4
8	8.4	9.8	10.5	11.8
10	10.8	12.2	12.9	14.2

QUALITY SYMBOLS MAJOR  CRITICAL 	DRAWN BY MengMeng		DATE 23/07/04			
	CHECKED BY XUZHONG		DATE 23/07/04			
GENERAL TOLERANCES (UNLESS SPECIFIED) X. ±0.5 .X ±0.25 .XX ±0.15 .XXX ±0.1 ANGLES ±2°	APPROVED BY XUZHONG		DATE 23/07/04		TITLE 1.2mm PITCH WTB WAFER CONNECTOR	
	UNITS mm				SIZE A4	
SCALE 1 : 1		SHEET NO. 1 OF 1		REV L		RFQ NO. NA
				DWG NO. 51273-XXXXX-XXX		